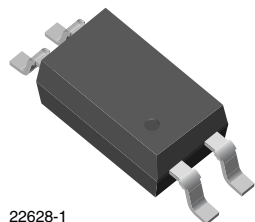
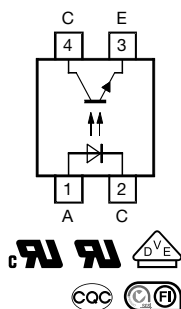




Optocoupler, Phototransistor Output, Single Channel, Half Pitch Mini-Flat Package



22628-1



FEATURES

- Low profile package (half pitch)
- AC isolation test voltage 3750 V_{RMS}
- Low coupling capacitance of typical 0.3 pF
- Current transfer ratio (CTR) selected into groups
- Low temperature coefficient of CTR
- Wide ambient temperature range
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS
COMPLIANT

LINKS TO ADDITIONAL RESOURCES



Product Page

DESCRIPTION

The TCMT110. series consist of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode in a 4 pin package.

The elements are mounted on one leadframe providing a fixed distance between input and output for highest safety requirements.

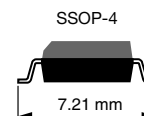
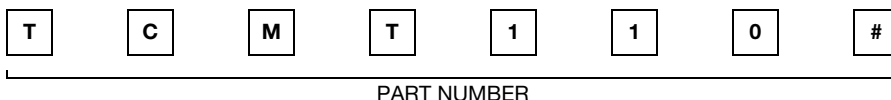
APPLICATIONS

- Programmable logic controllers
- Modems
- Answering machines
- General applications

AGENCY APPROVALS

- [UL 1577](#)
- [cUL](#)
- [DIN EN 60747-5-5 \(VDE 0884-5\)](#)
- [BSI](#)
- [CQC](#)
- [FIMKO](#)

ORDERING INFORMATION



AGENCY CERTIFIED / PACKAGE	CTR (%)									
	5 mA	10 mA				5 mA				
UL, cUL, FIMKO, BSI, VDE	50 to 600	40 to 80	63 to 125	100 to 200	160 to 320	50 to 150	100 to 300	80 to 160	130 to 260	200 to 400
SSOP-4	TCMT1100	TCMT1101	TCMT1102	TCMT1103	TCMT1104	TCMT1105	TCMT1106	TCMT1107, TCMT1107T3 ⁽¹⁾	TCMT1108	TCMT1109

Notes

- Available only on tape and reel
- ⁽¹⁾ Product is rotated 180° in tape and reel cavity



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	6	V
Forward current		I_F	60	mA
Forward surge current	$t_p \leq 10\text{ }\mu\text{s}$	I_{FSM}	1.5	A
Power dissipation		P_{diss}	100	mW
Junction temperature		T_j	125	$^{\circ}\text{C}$
OUTPUT				
Collector emitter voltage		V_{CEO}	70	V
Emitter collector voltage		V_{ECO}	7	V
Collector current		I_C	50	mA
Collector peak current	$t_p/T = 0.5, t_p \leq 10\text{ ms}$	I_{CM}	100	mA
Power dissipation		P_{diss}	150	mW
Junction temperature		T_j	125	$^{\circ}\text{C}$
COUPLER				
AC isolation test voltage (RMS)	Related to standard climate 23/50 DIN 50014	V_{ISO}	3750	V_{RMS}
Total power dissipation		P_{tot}	250	mW
Operating ambient temperature range		T_{amb}	-40 to +100	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +125	$^{\circ}\text{C}$
Soldering temperature ⁽¹⁾		T_{sld}	260	$^{\circ}\text{C}$

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability

⁽¹⁾ Refer to reflow profile for soldering conditions for surface mounted devices. Also refer to "Assembly Instructions" (www.vishay.com/doc?80054)

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Forward voltage	$I_F = 50\text{ mA}$	V_F	-	1.35	1.6	V
Junction capacitance	$V_R = 0, f = 1\text{ MHz}$	C_j	-	8		pF
OUTPUT						
Collector emitter voltage	$I_C = 100\text{ }\mu\text{A}$	V_{CEO}	70	-	-	V
Emitter collector voltage	$I_E = 100\text{ }\mu\text{A}$	V_{ECO}	7	-	-	V
Collector dark current	$V_{CE} = 20\text{ V}, I_F = 0\text{ A}$	I_{CEO}	-	-	100	nA
COUPLER						
Collector emitter saturation voltage	$I_F = 10\text{ mA}, I_C = 1\text{ mA}$	V_{CEsat}	-	-	0.3	V
Cut-off frequency	$V_{CE} = 5\text{ V}, I_F = 10\text{ mA}, R_L = 100\text{ }\Omega$	f_c	-	100	-	kHz
Coupling capacitance	$f = 1\text{ MHz}$	C_k	-	0.3	-	pF

Note

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements

CURRENT TRANSFER RATIO ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
I_C/I_F	$V_{CE} = 5\text{ V}, I_F = 5\text{ mA}$	TCMT1100	CTR	50	-	600	%
	$V_{CE} = 5\text{ V}, I_F = 10\text{ mA}$	TCMT1101	CTR	40	-	80	%
		TCMT1102	CTR	63	-	125	%
		TCMT1103	CTR	100	-	200	%
		TCMT1104	CTR	160	-	320	%
	$V_{CE} = 5\text{ V}, I_F = 5\text{ mA}$	TCMT1105	CTR	50	-	150	%
		TCMT1106	CTR	100	-	300	%
		TCMT1107	CTR	80	-	160	%
		TCMT1108	CTR	130	-	260	%
		TCMT1109	CTR	200	-	400	%

SWITCHING CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Delay time	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω, (see figure 1)	t _d	-	4.0	-	μs
Rise time	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω, (see figure 1)	t _r	-	5.5	-	μs
Fall time	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω, (see figure 1)	t _f	-	7.0	-	μs
Storage time	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω, (see figure 1)	t _s	-	1.5	-	μs
Turn-on time	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω, (see figure 1)	t _{on}	-	9.5	-	μs
Turn-off time	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω, (see figure 1)	t _{off}	-	8.5	-	μs
Turn-on time	V _S = 5 V, I _F = 10 mA, R _L = 1 kΩ, (see figure 2)	t _{on}	-	3.0	-	μs
Turn-off time	V _S = 5 V, I _F = 10 mA, R _L = 1 kΩ, (see figure 2)	t _{off}	-	20.0	-	μs

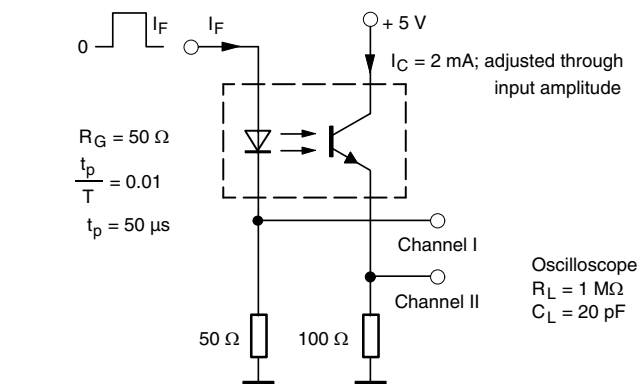


Fig. 1 - Test Circuit, Non-Saturated Operation

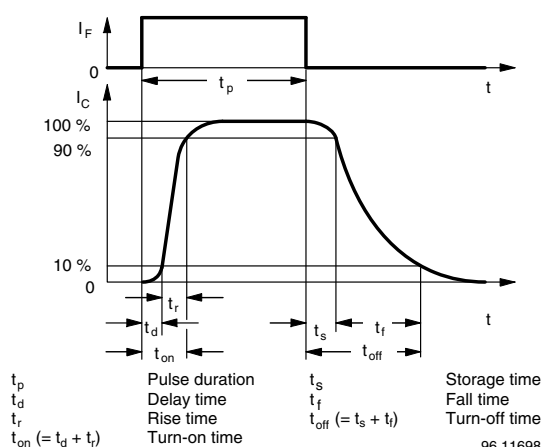


Fig. 3 - Switching Times

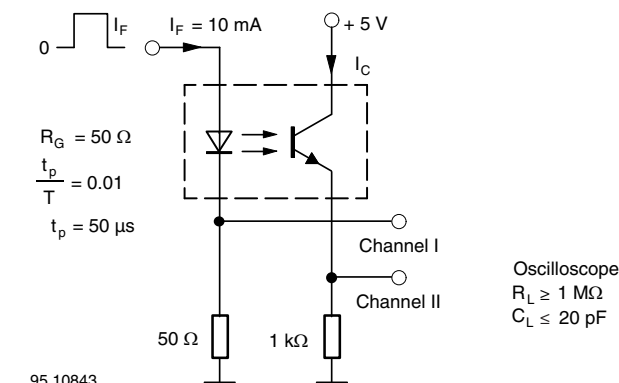


Fig. 2 - Test Circuit, Saturated Operation

SAFETY AND INSULATION RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		40 / 110 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, $t = 1$ min	V_{ISO}	3750	V_{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V_{IOTM}	6000	V_{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V_{IORM}	707	V_{peak}
Isolation resistance	$T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{12}$	Ω
	$T_{amb} = 100\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$		$\geq 10^{11}$	
	$T_{amb} = T_S$, $V_{IO} = 500\text{ V}$		$\geq 10^9$	
Output safety power		P_{SO}	350	mW
Input safety current		I_{SI}	150	mA
Input safety temperature		T_S	175	$^{\circ}\text{C}$
Creepage distance			≥ 5	mm
Clearance distance			≥ 5	mm
Insulation thickness		DTI	≥ 0.4	mm
Input to output test voltage, method B	$V_{IORM} \times 1.875 = V_{PR}$, 100 % production test with $t_M = 1$ s, partial discharge < 5 pC	V_{PR}	1326	V_{peak}
Input to output test voltage, method A	$V_{IORM} \times 1.6 = V_{PR}$, 100 % sample test with $t_M = 10$ s, partial discharge < 5 pC	V_{PR}	1132	V_{peak}

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

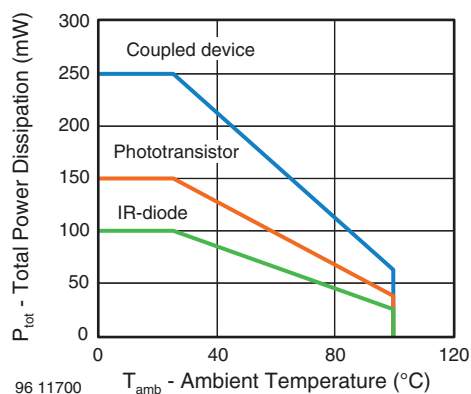


Fig. 4 - Total Power Dissipation vs. Ambient Temperature

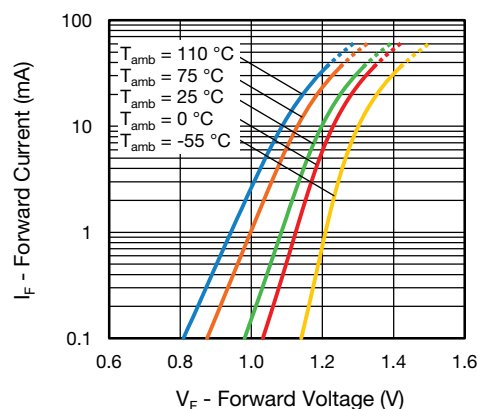


Fig. 5 - Forward Voltage vs. Forward Current

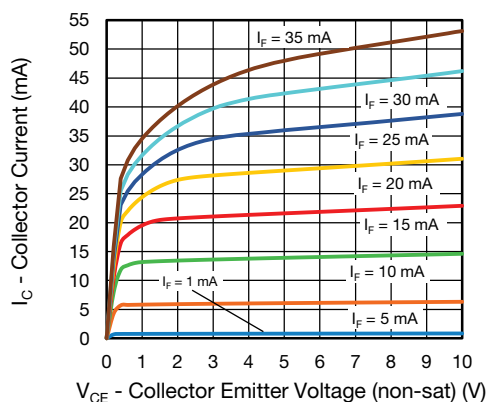


Fig. 6 - Collector Current vs. Collector Emitter Voltage

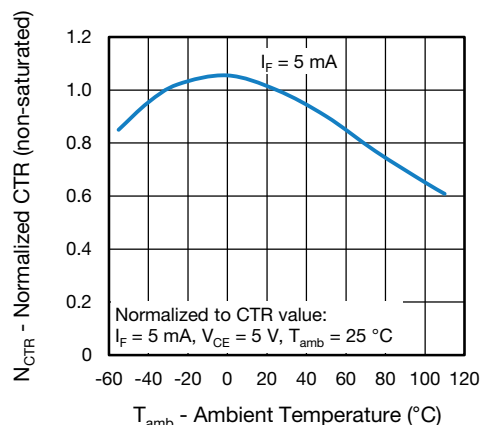


Fig. 9 - Normalized Current Transfer Ratio (non-saturated) vs. Ambient Temperature

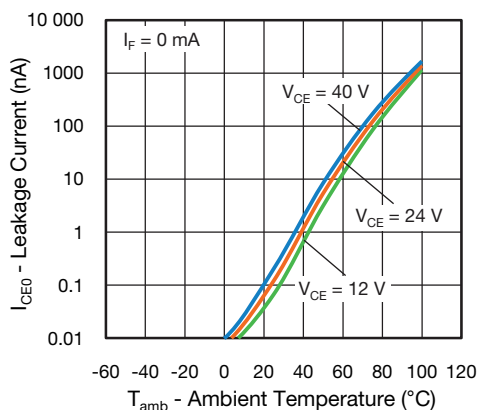


Fig. 7 - Leakage Current vs. Ambient Temperature

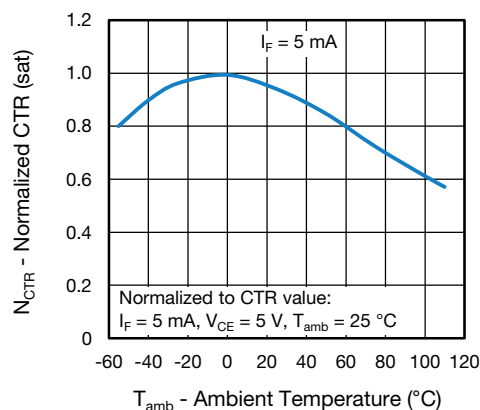


Fig. 10 - Normalized Current Transfer Ratio (saturated) vs. Ambient Temperature

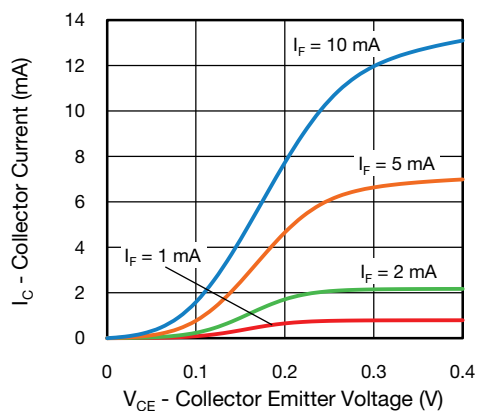


Fig. 8 - Collector Current vs. Collector Emitter Voltage

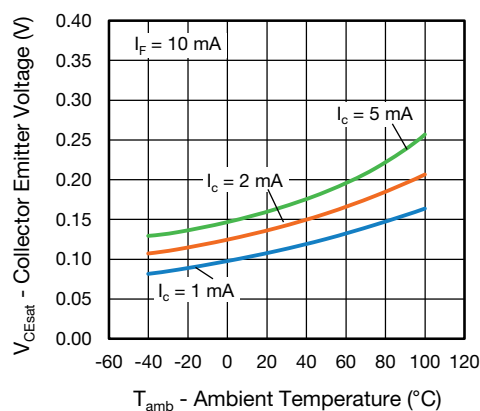


Fig. 11 - Collector Emitter Voltage vs. Ambient Temperature

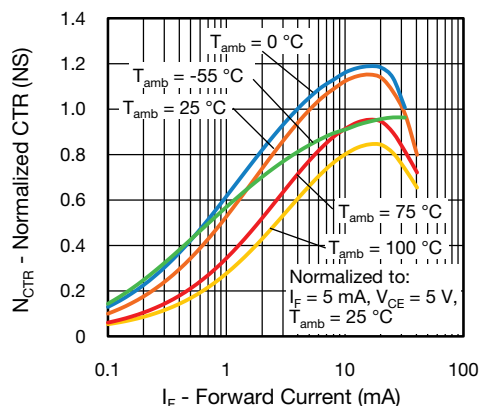


Fig. 12 - Normalized CTR (non-saturated) vs. Forward Current

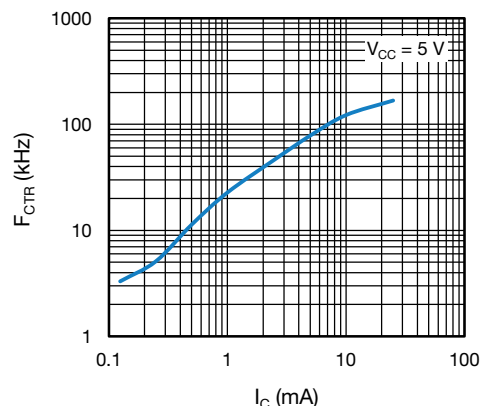


Fig. 15 - F_{CTR} vs. Collector Current

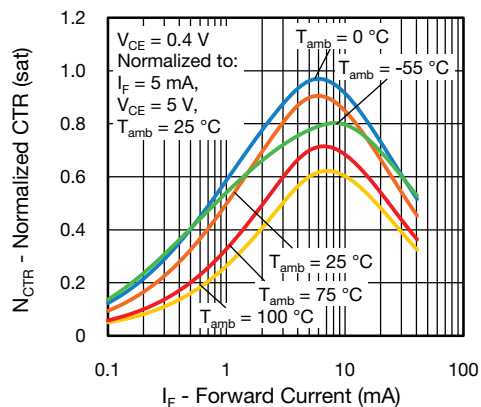


Fig. 13 - Normalized CTR (saturated) vs. Forward Current

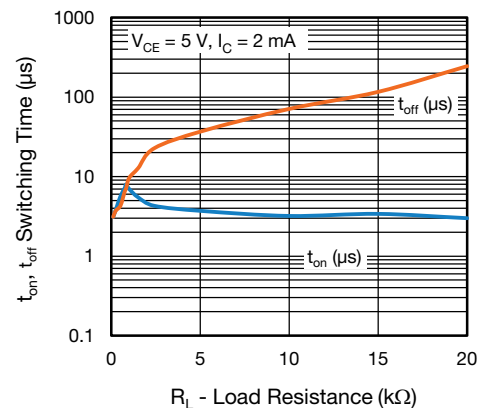


Fig. 16 - Switching Time vs. Load Resistance

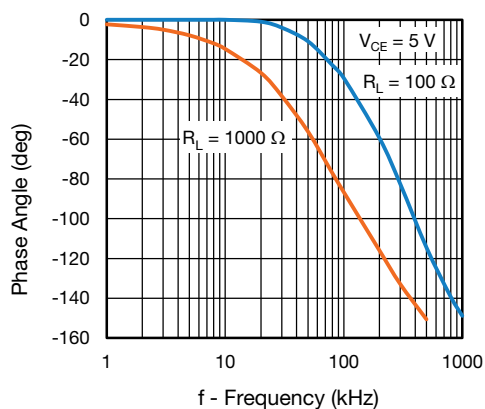
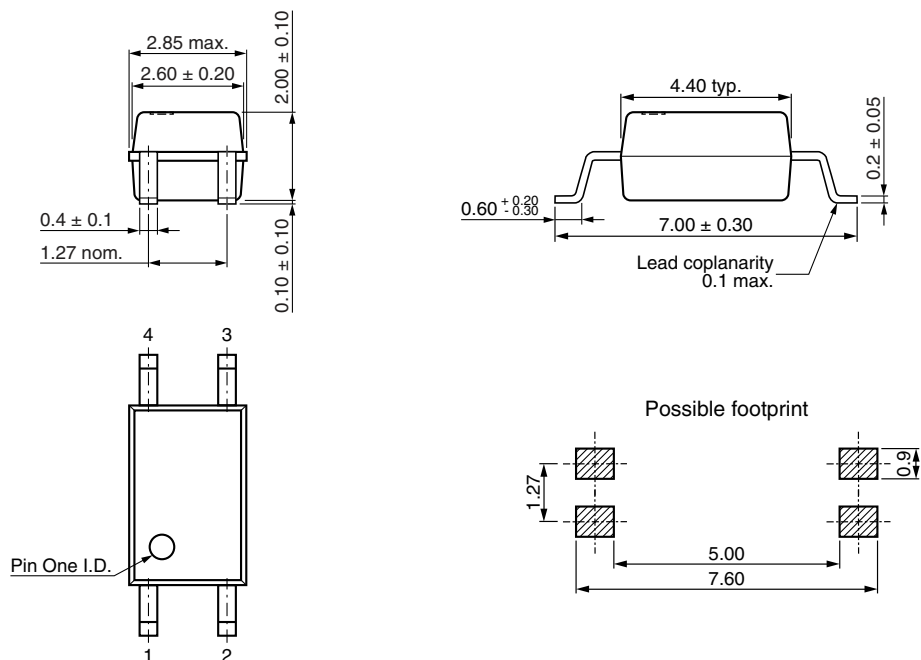


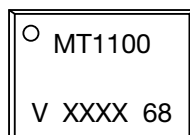
Fig. 14 - F_{CTR} vs. Phase Angle



PACKAGE DIMENSIONS in millimeters



PACKAGE MARKING (example)



Note

- XXXX = LMC (lot marking code)

TAPE AND REEL PACKAGING in millimeters

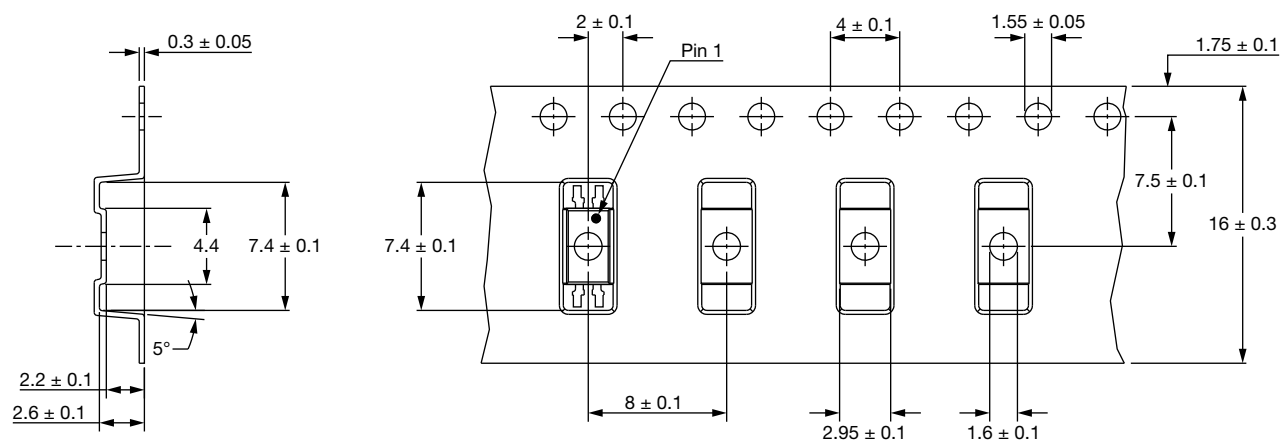
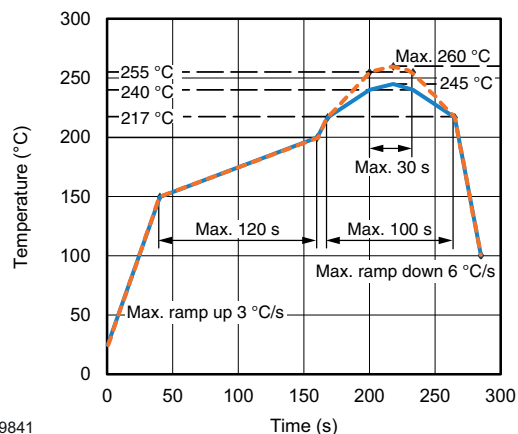


Fig. 17



SOLDER PROFILES



19841

Fig. 18 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2

Floor life: unlimited

Conditions: $T_{amb} < 30\text{ °C}$, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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